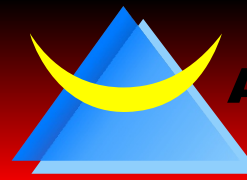


# Recommended Solder Reflow Methods

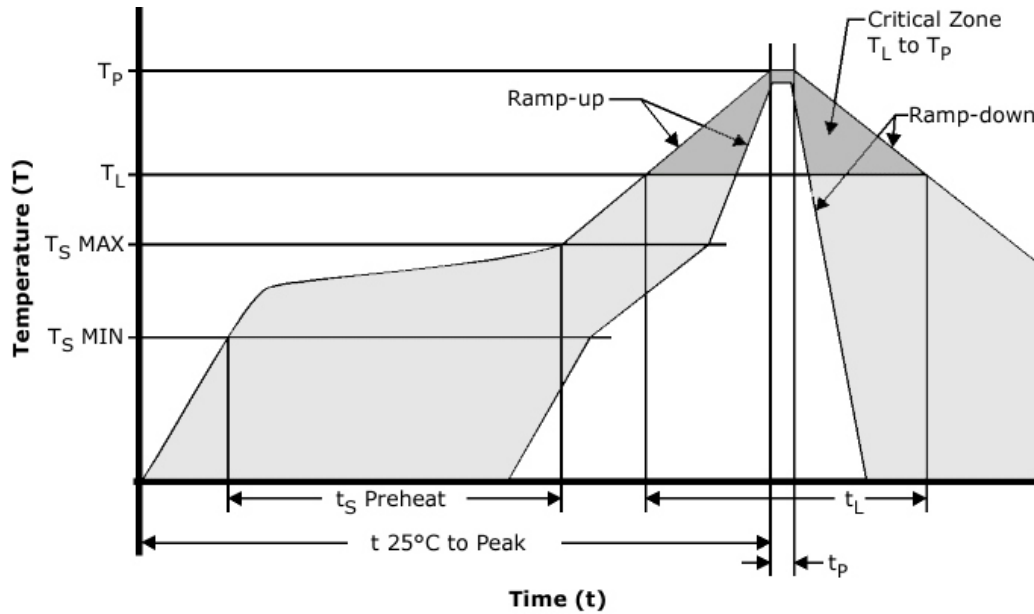
- T2A Series



**ASCEND**

FREQUENCY DEVICES

## Solder Reflow Profile



## Low Temperature Infrared/Convection

Note: Temperatures shown are applied to body of device

$T_S$ MAX to $T_L$ (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum ( $T_S$ MIN)	N/A
- Temperature Typical ( $T_S$ TYP)	150°C
- Temperature Maximum ( $T_S$ MAX)	N/A
- Time ( $t_s$ )	60 - 120 Seconds
Ramp-up Rate ( $T_L$ to $T_P$ )	5°C/second Maximum
Time Maintained Above:	
- Temperature ( $T_L$ )	150°C
- Time ( $t_L$ )	200 Seconds Maximum
Peak Temperature ( $T_P$ )	220°C Maximum
Target Peak Temperature ( $T_P$ Target)	220°C Maximum 1 Time / 215°C Maximum 1 Time
Time within 5°C of actual peak ( $t_p$ )	15 seconds Maximum 1 Time / 80 seconds Maximum 1 Time
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

## High Temperature Manual Soldering

**Note:** Temperatures listed are applied to body of device.  
260°C Maximum for 5 seconds Maximum, 2 times Maximum.

## Low Temperature Manual Soldering

**Note:** Temperatures listed are applied to body of device.  
185°C Maximum for 10 seconds Maximum, 2 times Maximum.